

- 10 -

CLAIMS:

1. A method of forming a wire bond bonding a wire to a connection pad of an electronic device comprising the steps of:
  - 5 forming a first bump ball on the connection pad; and then  
forming a second bump ball on the connection pad that is contiguous with the first bump ball.
- 10 2. A method as claimed in claim 1, including extending the wire from the second bump ball.
3. A method as claimed in claim 1, wherein the second bump ball partially lies on the connection pad and partially lies on the first bump ball.
- 15 4. A method as claimed in claim 1, including severing the wire from the first bump ball prior to forming the second bump ball.
- 20 5. A method as claimed in claim 4, including edging the first bump ball and forming a recessed portion in the bump ball prior to forming the second bump ball.
6. A method as claimed in claim 5, wherein the second bump ball is formed on the recessed portion of the first bump ball.
- 25 7. A method as claimed in claim 1, including the step of forming an additional bump ball that is contiguous with the first and/or second bump ball.
8. A method as claimed in claim 7, including extending the wire from the additional bump ball.
- 30 9. A method as claimed in claim 7, including severing the wire from the second bump ball prior to forming the additional bump ball.

- 11 -

10. A method as claimed in claim 7, including edging the first and/or second bump ball and forming a recessed portion in the first and/or second bump ball prior to forming the additional bump ball.
- 5 11. A method as claimed in claim 9, wherein the additional bump ball is formed on the recessed portion of the first or second bump ball.
12. A method as claimed in claim 1, wherein the diameter of the wire is less than 50µm.
- 10 13. A wire bond bonding a wire to a connection pad of an electronic device comprising a first bump ball formed on the connection pad and a second bump ball formed on the connection pad that is contiguous with the first bump ball.
- 15 14. A wire bond as claimed in claim 13, wherein the wire extends from the second bump ball.
- 20 15. A wire bond as claimed in claim 13, wherein the second bump ball partially lies on the connection pad and partially lies on the first bump ball.
16. A wire bond as claimed in claim 13, wherein the first bump ball comprises a recessed portion.
- 25 17. A wire bond as claimed in claim 16, wherein the second bump ball is positioned on the recessed portion of the first bump ball.
18. A wire bond as claimed in claim 13, including an additional bump ball that is contiguous with the first and/or second bump ball.
- 30 19. A wire bond as claimed in claim 13, wherein the wire extends from the additional bump ball.

- 12 -

20. A wire bond as claimed in claim 13, wherein the first or second bump ball comprises a recessed portion and the additional bump ball is positioned on the recessed portion of the first or second bump ball.